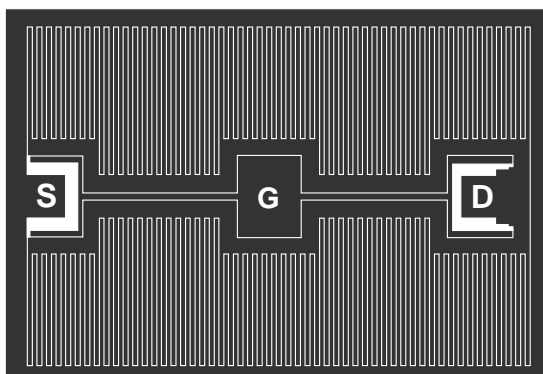


LP07



Backside Potential: Drain <sup>4</sup>

All dimensions in mils.

Die Geometry	Dimensions			Backside Metal	Bonding Pads <sup>2</sup>		Recommended Assembly Material		
	Length <sup>1</sup>	Width <sup>1</sup>	Thickness		Material	Size	Wire <sup>3</sup>	Wire Size <sup>3</sup>	Preform
LP07	50	70	11 ± 1.5	None	Al-Cu-Si	4.7 x 4.7	Au or Al	1.5	Epoxy

**Notes:**

1. Maximum values
2. Bond pad size are for all three pads.
3. Bond wire size and material depends on AuTCB, TSB or Al USB.
4. Drain pad bonding is required.

11/19/02